Pr paration of substrate capabl of being dismantl d includ s formation of int rface betw en thin lay r and substrat by mol cular adh sion in controll d manner

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Inventor(s): ASPAR BERNARD; GHYSELEN BRUNO; MORICEAU HUBERT; RAYSSAC OLIVIER

Applicant(s): COMMISSARIAT ENERGIE ATOMIQUE (FR)

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Abstract

The preparation of a substrate capable of being dismantled, includes the formation of an interface by gluing by molecular adhesion of a face of a layer on a face of a substrate, in which is provided an appropriate treatment step to put the mechanical behavior at the interface to a controlled level essentially inferior to the maximum possible. An Independent claim is also included for a substrate capable of being dismantled and prepared by the above process.

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